

**LTM8031 71LD 15.00mm X 9.00mm X 2.82mm (TABLE OF MATERIAL DECLARATION)**

*The LTM8031 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

**It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)**

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1547	Barium Compounds	7727-43-7	0.00232	1.50
				Filler Substances (Silica Crystalline)	105391-331,115651-0/9003-36-5,21645-51-2	0.06175	39.91
				Copper Metal	7440-50-8	0.08663	56.00
				Copper Compounds	1328-53-6	0.00003	0.02
				Ecotoxic substances	7439-92-1	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00071	0.46
				Nickel	7440-02-0	0.00325	2.10
				Zinc	7440-66-6	0.00001	0.01
2	Solder Paste	Alloy	0.0045	Sn	7440-31-5	0.00428	95.00
				Sb	7440-36-0	0.00023	5.00
3	Epoxy		0.0018	Di-ester resin	-	0.00018	10.00
				Functionalized ester	-	0.00018	10.00
				Silver	7440-22-4	0.00144	80.00
4	Passive/Active Components		0.5558	Iron Powder (Fe)	7439-89-6	0.29864	53.73
				Copper (Cu)	7440-50-8	0.19325	34.77
				Nickel (Ni)	7440-02-0	0.00855	1.54
				Tin (Sn)	7440-31-5	0.00285	0.51
				Ceramic (Ba Compounds)	12047-27-7	0.05250	9.45
5	Active Ics	Silicon	0.0025	Silicon	7440-21-3	0.00251	100.00
6	Wire	Gold	0.0005	Au	7440-57-5	0.00050	99.99
7	Encapsulation	Epoxy Resin	0.4923	Fused Silica	60676-86-0	0.38006	77.20
				Epoxy Resin	-	0.04381	8.90
				Phenol Resin	-	0.04381	8.90
				Crytalline Silica	14808-60-7	0.01477	3.00
				Carbon Black	1333-86-4	0.00246	0.50
				Metal Hydroxide	-	0.00738	1.50
Total Package Weight			1.2121				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts